1.1 Scope.

This specification covers the detail requirements for a 12-bit resolution A/D converter with complete microprocessor interface and a high performance buried Zener reference.

1.2 Part Number.

The complete part number per Table 1 of this specification is as follows:

Device	Part Number[1]
−1	AD574AS(X)/883B
−2	AD574AT(X)/883B
−3	AD574AU(X)/883B

NOTE
[1]See paragraph 1.2.3 for package identifier.

1.2.3 Case Outline.

See Appendix 1 of General Specification ADI-M-1000: package outline:

(X)	Package	Description
D	D-28	28-Pin DIP
E	E-28A	28-Pin LCC

1.3 Absolute Maximum Ratings. (T_A = +25°C unless otherwise noted)

V_{CC} to Digital Common	+16.5V
V_{EE} to Digital Common	−16.5V
V_{LOGIC} to Digital Common	+7V
Analog Common to Digital Common	±1V
Control Inputs (CE, $\overline{CS}$, A_0, 12/$\overline{8}$, R/$\overline{C}$) to Digital Common	−0.5V to V_{LOGIC} +0.5V
Analog Inputs (REF IN, BIP OFF, $10V_{IN}$) to Analog Common	±16.5V
$20V_{IN}$ to Analog Common	±24V
REF OUT	Indefinite Short to Common Momentary Short to V_{CC}
Power Dissipation	1000mW
Storage Temperature Range	−65°C to +150°C
Lead Temperature (Soldering 10sec)	+300°C

1.5 Thermal Characteristics.

Thermal Resistance θ_{JC} = 25°C/W for D-28 or E-28A
θ_{JA} = 60°C/W for D-28 or E-28A

AD574A—SPECIFICATIONS

Table 1.

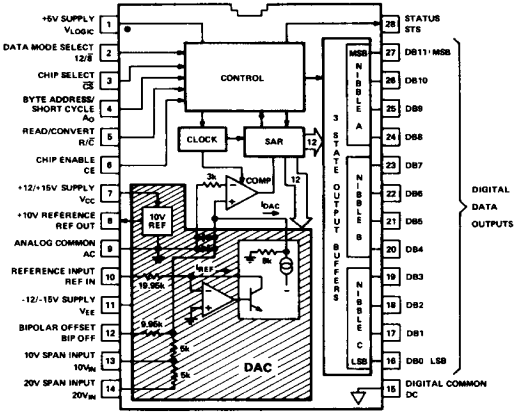
Test	Symbol	Device	Design Limit @ +25°C	Sub Group 1	Sub Group 2, 3	Sub Group 4	Test Condition[1]	Units
Power Dissipation	P_D	−1, 2, 3	725	725			Tristated Outputs	mW max
Input Resistance	R_{IN}	−1, 2, 3	3	3			10V Span	kΩ min
			7	7				kΩ max
			6	6			20V Span	kΩ min
			14	14				kΩ max
Internal 10V Reference Output Voltage Error	V_{REF}	−1, 2	±20	±20			Bipolar 1.5mA External Load	mV
		−3	±10	±20		±10		
Logic Input High[2]	V_{IH}	−1, 2, 3	2.0	2.0				+ V min
CE, $\overline{CS}$, R/$\overline{C}$, A_0			5.5					+ V max
Logic Input Low[2]	V_{IL}	−1, 2, 3	0.5					− V min
CE, $\overline{CS}$, R/$\overline{C}$, A_0			0.8	0.8				+ V max
Logic Input Current CE, $\overline{CS}$, R/$\overline{C}$, A_0	I_{LIN}	−1, 2, 3	20	20	20		V_{IH} = 5.0V V_{IL} = 0.0V	±μA max
Logic Output High DB11-DB0	V_{OH}	−1, 2, 3	2.4	2.4	2.4		I_{SOURCE} = 500μA	+ V min
Logic Output Low DB11-DB0, STS	V_{OL}	−1, 2, 3	0.4	0.4	0.4		I_{SINK} = 1.6mA	+ V max
Three-State Output Leakage DB11-DB0	I_{OLT}	−1, 2, 3	20	20	20		Outputs Tristated V_{IH} = 5.0V	±μA max
Power Supply Current	I_L	−1, 2, 3	40	40			Outputs Tristated	mA max
	I_{CC}	−1, 2, 3	5	5				
	I_{EE}	−1, 2, 3	30	30				
Full-Scale Calibration Drift	TCA_E	−1			20			± LSB max
		−2			10			
		−3			5			
Linearity	LE	−1	1	1	1		10V Unipolar, 20V Bipolar Major Transitions	± LSB max
		−2, 3	1/2	1	1	1/2		
Differential Nonlinearity[3]	DNL	−1	11	11	11		All Codes Tested	Bits min
		−2, 3	12	11	12	12		
Power Supply Rejection Ratio[4]	PSRR	−1	2	2			See Note 5	± LSB max
		−2, 3	1	2		1		
	PSRR	−1, 2, 3	1/2	1/2			See Note 6	
	PSRR	−1	2	2			See Note 7	
		−2, 3	1	2		1		
Unipolar Offset Error	V_{OSE}	−1	2	2	4			± LSB max
		−2, 3	1	2	2	1		
Unipolar Offset Drift	TC_{VOS}	−1			2			± LSB max
		−2, 3			1			
Bipolar Offset Error	B_{POE}	−1	4	4	8		Bipolar 20V Span	± LSB max
		−2	4	4	6			
		−3	2	4	3	2		
Bipolar Offset Drift	TCB_{POE}	−1			4		Bipolar 20V Span	± LSB max
		−2			2			
		−3			1			
Full-Scale Error	A_B	−1, 2	0.25	0.25			Bipolar 20V Span	± %/FSR max
		−3	0.125	0.25		0.125		
	A_U	−1, 2	0.25				Unipolar 10V Span	± %/FSR max
		−3	0.125					

Test	Symbol	Device	Design Limit @ +25°C	Sub Group 1	Sub Group 2, 3	Sub Group 9	Test Condition[1]	Units
Full-Control Mode[1]								
STS Delay from CE	t_{DSC}	−1, 2, 3	400			350	Timing Per Figure 1	ns max
CE Pulse Width	t_{HEC}	−1, 2, 3	300			300	Timing Per Figure 1	ns min
Access Timing (from CE)[8]	t_{DD}	−1, 2, 3	200			200	Timing Per Figure 2	ns max
Output Float Delay	t_{HL}	−1, 2, 3	100			100	Timing Per Figure 2	ns max
Data Valid After CE Low	t_{HD}	−1, 2, 3	25			25	Timing Per Figure 2	ns min
Stand-Alone Mode[1]								
Low R/$\overline{C}$ Pulse Width	t_{HRL}	−1, 2, 3	250			250	Timing Per Figure 3	ns min
STS Delay from R/$\overline{C}$	t_{DS}	−1, 2, 3	600			600	Timing Per Figure 3	ns max
Data Access Time[8]	t_{DDR}	−1, 2, 3	250			250	Timing Per Figure 3	ns max
Data Valid After R/$\overline{C}$Low	t_{HDR}	−1, 2, 3	25			25	Timing Per Figure 3	ns min
Conversion Time	t_C	−1, 2, 3	35			35	To 12 Bits	µs max
			24			24	To 8 Bit	

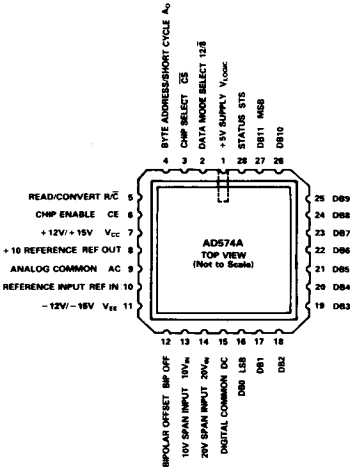
NOTES
[1] V_{CC} = +15V, V_{EE} = −15V, V_{LOGIC} = +5V, 12/$\overline{8}$ connected to V_{LOGIC}, A_0 and $\overline{CS}$ at logic "0", CE at logic "1." 10V unipolar configuration unless otherwise noted.
10V Unipolar: 50Ω resistor Pin 8 to Pin 10, 50Ω resistor Pin 12 to ground, analog input to Pin 13.
20V Bipolar: 50Ω resistor Pin 8 to Pin 12, 50Ω resistor Pin 8 to Pin 10, analog input to Pin 14.
See Figures 1, 2, and 3 for timing information.
[2] V_{IH} = 2.0V min and V_{IL} = 0.8V max, guaranteed design limits −55°C to +125°C.
[3] Minimum resolution for which no missing codes are guaranteed.
[4] Change in unipolar 10V span with full-scale (Code 4095) transition voltage.
[5] Test Conditions for PSRR:
13.5V ≤ V_{CC} ≤ 16.5V, V_{LOGIC} = 5V, V_{EE} = −15V
11.4V ≤ V_{CC} ≤ 12.6V, V_{LOGIC} = 5V, V_{EE} = −12V
[6] 4.5V ≤ V_{LOGIC} ≤ 5.5V, V_{CC} = 15V, V_{EE} = −15V
[7] −16.5 ≤ V_{EE} ≤ −13.5V, V_{LOGIC} = 5V, V_{CC} = 15V
−12.6V ≤ V_{EE} ≤ −11.4V, V_{LOGIC} = 5V, V_{CC} = 12V
[8] See Figure 4.

3.2.1 Functional Block Diagram and Terminal Assignments.

D Package (DIP)



E Package (LCC)

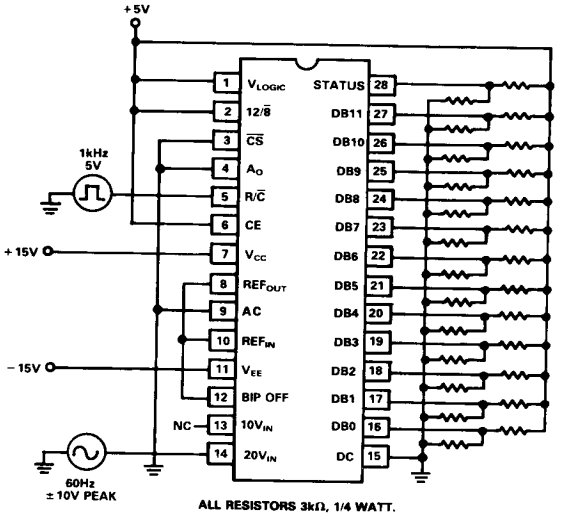


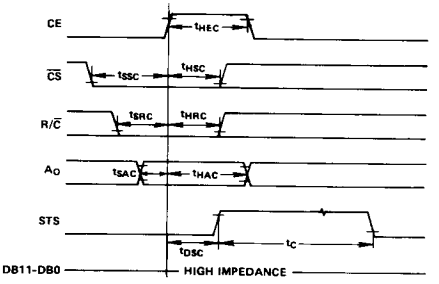
3.2.4 Microcircuit Technology Group.

This microcircuit is covered by technology group (57).

4.2.1 Life Test/Burn-In Circuit.

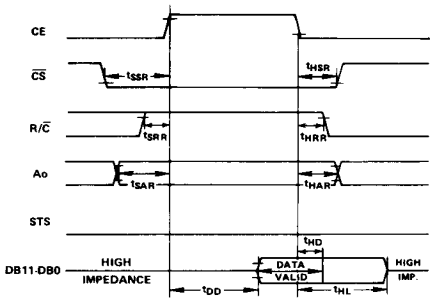
Steady state life test is per MIL-STD-883 Method 1005. Burn-in is per MIL-STD-883 Method 1015 test condition (B).





Symbol	Parameter	Min	Typ	Max	Units
t_{DSC}	STS Delay from CE			400	ns
t_{HEC}	CE Pulse Width	300			ns
t_{SSC}	CS to CE Setup	50			ns
t_{HSC}	CS Low During CE High	200			ns
t_{SRC}	R/C to CE Setup	50			ns
t_{HRC}	R/C Low During CE High	200			ns
t_{SAC}	A_0 to CE Setup	0			ns
t_{HAC}	A_0 Valid During CE High	300			ns
t_C	Conversion Time				
	8-Bit Cycle	10		24	µs
	12-Bit Cycle	15		35	µs

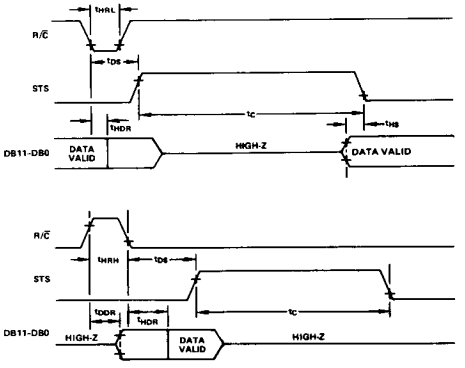
Figure 1. Convert Start Timing



Symbol	Parameter	Min	Typ	Max	Units
t_{DD}[1]	Access Time (from CE)			200	ns
t_{HD}	Data Valid after CE Low	25			ns
t_{HL}[2]	Output Float Delay			100	ns
t_{SSR}	$\overline{CS}$ to CE Setup	150			ns
t_{SRR}	R/$\overline{C}$ to CE Setup	0			ns
t_{SAR}	A_0 to CE Setup	150			ns
t_{HSR}	$\overline{CS}$ Valid After CE Low	50			ns
t_{HRR}	R/$\overline{C}$High After CE Low	0			ns
t_{HAR}	A_0 Valid After CE Low	50			ns

[1] t_{DD} is measured with the load circuit of Figure 4 and defined as the time required for an output to cross 0.4V to 2.4V.
[2] t_{HL} is defined as the time required for the data lines to change 0.5V when loaded with the circuit of Figure 5.

Figure 2. Read Timing



Symbol	Parameter	Min	Typ	Max	Units
t_{HRL}	Low R/$\overline{C}$ Pulse Width	250			ns
t_{DS}	STS Delay from R/$\overline{C}$			600	ns
t_{HDR}	Data Valid After R/$\overline{C}$ Low	25			ns
t_{HS}	STS Delay After Data Valid	300		1000	ns
t_{HRH}	High R/$\overline{C}$ Pulse Width	300			ns
t_{DDR}	Data Access Time			250	ns

Figure 3. Stand-Alone Mode Timing

a. High-Z to Logic 1 *b. High-Z to Logic 0*

Figure 4. Load Circuit for Access Timing Test

a. Logic 1 to High-Z *b. Logic 0 to High-Z*

Figure 5. Load Circuit for Output Float Delay Test